Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanisms

EESTI STANDARDIKESKUS
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EESTI STANDARDI EESSÕNA NATIONAL FOREWORD

See Eesti standard EVS-EN 62435-2:2017 sisaldab Euroopa standardi EN 62435-2:2017 ingliskeelset teksti.	This Estonian standard EVS-EN 62435-2:2017 consists of the English text of the European standard EN 62435-2:2017.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
Euroopa standardimisorganisatsioonid on teinud Euroopa standardi rahvuslikele liikmetele kättesaadavaks 28.04.2017.	Date of Availability of the European standard is 28.04.2017.
Standard on kättesaadav Eesti Standardikeskusest.	The standard is available from the Estonian Centre for Standardisation.

Tagasisidet standardi sisu kohta on võimalik edastada, kasutades EVS-i veebilehel asuvat tagasiside vormi või saates e-kirja meiliaadressile standardiosakond@evs.ee.

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Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanisms (IEC 62435-2:2017)

Composants électroniques - Stockage de longue durée des dispositifs électroniques à semiconducteurs - Partie 2: Mécanismes de détérioration (IEC 62435-2:2017)

Elektronische Bauteile - Langzeitlagerung elektronischer Halbleiterbauelemente - Teil 2: Schädigungsmechanismen (IEC 62435-2:2017)

European Committee for Electrotechnical Standardization
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European foreword

The text of document 47/2327/FDIS, future edition 1 of IEC 62435-2, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62435-2:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-11-28
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-02-28

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 62435-2:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-17:1994	NOTE	Harmonized as EN 60068-2-17:1994 (not modified).
IEC 60068-2-20:2008	NOTE	Harmonized as EN 60068-2-20:2008 (not modified).
IEC 60721-3-1	NOTE	Harmonized as EN 60721-3-1.
IEC 60721-3-3	NOTE	Harmonized as EN 60721-3-3.
IEC 60749-21	NOTE	Harmonized as EN 60749-21.
IEC 61340-5-1:2007	NOTE	Harmonized as EN 61340-5-1:2007 (not modified).
IEC/TR 61340-5-2:2007	NOTE	Harmonized as CLC/TR 61340-5-2:2008 (not modified).
IEC 61760-4	NOTE	Harmonized as EN 61760-4.
IEC/TR 62258-3	NOTE	Harmonized as CLC/TR 62258-3.
IEC 62435-1	NOTE	Harmonized as EN 62435-1.
IEC 62435-4 [1)]	NOTE	Harmonized as EN 62435-4 [1)].
IEC 62435-5	NOTE	Harmonized as EN 62435-5.

1) At draft stage.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60749-20-1	-	Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat	EN 60749-20-1	-

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INTRODUCTION

This document applies to the long-term storage of electronic components.

This is a document for long-term storage (LTS) of electronic devices drawing on the best long-term storage practices currently known. For the purposes of this document, LTS is defined as any device storage whose duration can be more than 12 months for product scheduled for long duration storage. While intended to address the storage of unpackaged semiconductors and packaged electronic devices, nothing in this standard precludes the storage of other items under the storage levels defined herein.

Although it has always existed to some extent, obsolescence of electronic components and particularly of integrated circuits, has become increasingly intense over the last few years.

Indeed, with the existing technological boom, the commercial life of a component has become very short compared with the life of industrial equipment such as that encountered in the aeronautical field, the railway industry or the energy sector.

The many solutions enabling obsolescence to be resolved are now identified. However, selecting one of these solutions should be preceded by a case-by-case technical and economic feasibility study, depending on whether storage is envisaged for field service or production, for example:

- remedial storage as soon as components are no longer marketed;
- preventive storage anticipating declaration of obsolescence.

Taking into account the expected life of some installations, sometimes covering several decades, the qualification times, and the unavailability costs, which can also be very high, the solution to be adopted to resolve obsolescence should often be rapidly implemented. This is why the solution retained in most cases consists in systematically storing components which are in the process of becoming obsolescent.

The technical risks of this solution are, a priori, fairly low. However, it requires perfect mastery of the implemented process and especially of the storage environment, although this mastery becomes critical when it comes to long-term storage.

All handling, protection, storage and test operations are recommended to be performed according to the state of the art.

The application of the approach proposed in this standard in no way guarantees that the stored components are in perfect operating condition at the end of this storage. It only comprises a means of minimizing potential and probable degradation factors.

Some electronic device users have the need to store electronic devices for long periods of time. Lifetime buys are commonly made to support production runs of assemblies that well exceed the production timeframe of its individual parts. This puts the user in a situation requiring careful and adequate storage of such parts to maintain the as-received solderability and minimize any degradation effects to the part over time. Major degradation concerns are moisture, electrostatic fields, ultra-violet light, large variations in temperature, air-borne contaminants, and outgassing.

Warranties and sparing also present a challenge for the user or repair agency as some systems have been designated to be used for long periods of time, in some cases for up to 40 years or more. Some of the devices needed for repair of these systems will not be available from the original supplier for the lifetime of the system or the spare assembly may be built with the original production run but then require long-term storage. This document was developed to provide a standard for storing electronic devices for long periods of time.

For storage of devices that are moisture sensitive but that do not need to be stored for long periods of time, refer to IEC TR 62258-3.

Long-term storage assumes that the device is going to be placed in uninterrupted storage for a number of years. It is essential that it is useable after storage. Particular attention should be paid to storage media surrounding the devices together with the local environment.

These guidelines do not imply any warranty of product or guarantee of operation beyond the storage time given by the manufacturer.

The IEC 62435 series is intended to ensure that adequate reliability is achieved for devices in user applications after long-term storage. Users are encouraged to request data from suppliers to these specifications to demonstrate a successful storage life as requested by the user. These standards are not intended to address built-in failure mechanisms that would take place regardless of storage conditions

These standards are intended to give practical guide to methods of long-duration storage of electronic components where this is intentional or planned storage of product for a number of years. Storage regimes for work-in-progress production are managed according to company internal process requirements and are not detailed in this series of standards.

The overall standard includes a number of parts. Parts 1 to 4 apply to any long-term storage and contain general requirements and guidance, whereas Parts 5 to 9 are specific to the type of product being stored. It is intended that the product specific part should be read alongside the general requirements of Parts 1 to 4.

Electronic components requiring different storage conditions are covered separately starting with Part 5.

The structure of the IEC 62435 series as currently conceived is as follows:

Part 1 – General

Part 2 – Deterioration mechanisms

Part 3 – Data

Part 4 – Storage

Part 5 – Die and wafer devices

Part 6 – Packaged or finished devices

Part 7 – MEMS

Part 8 – Passive electronic devices

Part 9 – Special cases